



Plating Process

Plating Equipment
for Semiconductor Panel Level Packaging

Technical Specifications

Plating Equipment

Panel Size (mm)	300/ 500/ 600/ 700
Anode	Insoluble/ Multiple Zone
Convection/Agitation	Paddle Type & Fan Type
Membrane	Ionic Exchange Membrane
Warpage allowance	Max. ≤ 10 mm
Cathode Contact Failure Detection	Yes
Blanket uniformity	$> 95\%$
Application	RDL Trace & Via Filling Copper Bump & Pillar Plating Stud & Heat Sink Plating
Type of carrier substrate	Stainless, Epoxy, Glass & CCL (FR-4)

Description

Process flow	Loading→Micro Etch→Acid Rinse→Cu Plating→Water Rinse→Dry→Unloading
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*Specific performance parameters depend on the application.



→ Features

- **Hassle-Free Operation**
Jig-free design for easy handling, less maintenance, and maximum uptime.
- **Scalable & Flexible**
Modular design expands with your needs and simplifies maintenance.
- **Superior Plating Quality**
Multi-anode system delivers $>95\%$ uniformity and minimizes edge effects.
- **High-Performance Capability**
Achieves copper thickness beyond $150 \mu\text{m}$ with >15 ASD for advanced applications.
- **Smart CMS Integration**
Inline chemical monitoring with automatic dosing for stable process control.

